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UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO.

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Page 1 of 1

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INVENTOR(S) : Masahiko Yanagisawa

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page, Item [54] and Column 1, lines1-4,

Title, "FLEXIBLE INTERCONNECT SUBSTRATE OF A TAPE-SHAPED SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE AND CIRCUIT BOARD" should read -- A FLEXIBLE INTERCONNECT SUBSTRATE OF A TAPE-SHAPED SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE AND CIRCUIT BOARD --

Signed and Sealed this

Seventeenth Day of May, 2005

JON W. DUDAS Director of the United States Patent and Trademark Office